



Certificate of Compliance

DUNS		Document Date	URL for Additional Information
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Material Declaration Processing Information

FSID	Material Declaration	Site Owner	Assembly Location	Package Weight(g)	MSL Rating
FQH8N100C	TO-247-3 (G)	SUZHOU	INTERNAL SUZHOU	5.4569250	Not Applicable
Terminal Finish	Base Alloy	Green Status	Reflow Cycles	Max Time at Temp	Peak Temp
Matte Tin (Sn)	CU Alloy	This product is green as defined by Fairchild's Green Policy. Please use this link to access Fairchild's Green Product Definition. Fairchild's Green Policy	Not Applicable		

Homogenous Material Composition Declaration

Component	Material	Weight of Component(mg)	Substance	Weight (mg)	CAS	PPM in FSID
Chip	Other inorganic materials	32.0000	Silicon	32.0000	7440-21-3	5864
Die Attach	Other Nonferrous metals & alloys	35.0250	Lead	32.4000	7439-92-1	5937
			Silver	0.8750	7440-22-4	160
			Tin	1.7500	7440-31-5	321
Encapsulation	Thermoplastics	1740.0000	Carbon Black	17.4000	1333-86-4	3189
			Epoxy Resin	348.0000	29690-82-2	63772
			Silica, vitreous	1374.6000	60676-86-0	251900
Lead Frame	Copper & its alloys	3612.9000	Copper	3490.0000	7440-50-8	639554
			Iron	2.1000	7439-89-6	385
			Nickel	118.0000	7440-02-0	21624
			Phosphorus	1.0500	7723-14-0	192
			Zinc	1.7500	7440-66-6	321
Plating	Other Nonferrous metals & alloys	31.0000	Tin	31.0000	7440-31-5	5681
Wire Bond	Aluminum & its alloys	6.0000	Aluminum	6.0000	7429-90-5	1100

Note: The substance content disclosed herewith is approximate and is based on various methods including, engineering calculations, supplier surveys, Material Safety Data Sheets, analytical measurements. Fairchild may update this document without notification.

Additionally, the following should be noted:

- This statement may not include information regarding the miniscule quantities of dopant and metal materials in the electrical devices contained within the finished product.
- CAS numbers listed for Resin substances are generic and may contain alternate substances of similar composition.

RoHS Declaration

The European Parliament and of the Council on the Restriction of the use of Certain Hazardous Substances in Electrical and Electronic Equipment (RoHS) directive restricts the concentration of Lead (Pb), Mercury (Hg), Hexavalent Chromium (Cr6+), Polybrominated Biphenyls (PBB), Polybrominated Diphenyl Ethers (PBDE) to 0.1% (1000 PPM) and restricts the concentration of Cadmium (Cd) to 0.01% (100 PPM) in homogeneous materials of electronic products.

The FSC part number listed above and the homogenous materials in the product are compliant with the Directive 2011/65/EU.

Exemptions as declared for the directive are:

7(a)-Lead in high melting temperature type solders (i.e. lead based solder alloys containing 85 % by weight or more lead).

China RoHS

With the possible exception of lead, if applicable (refer to the RoHS Declaration statement above), this product and all homogeneous materials in the product comply with the China RoHS standard SJ/T 11363-2006.

REACH Compliance

European Union Regulation (EC) No 1907/2006 concerning the Registration, Evaluation, Authorization, and Restriction of Chemicals (REACH) entered into force on June 1, 2007. Fairchild Semiconductor agrees with the purpose of REACH, which is to ensure a high level of protection of human health and the environment. Fairchild semiconductor is compliant with all applicable requirements of REACH and upon request will provide information regarding the chemical composition of our products.

Fairchild Semiconductor is neither a manufacturer nor importer of preparations into Europe and therefore the registration requirements of REACH do not apply to us. It is expected that any electronic materials manufacturer that uses preparations from Europe in their products will ensure compliance with REACH registration requirements.

Product (articles) manufacturers or importers into Europe are obligated under Article 33 of REACH to inform recipients of any articles that contain chemicals on the Substances of Very High Concern (SVHC) candidate list above a 0.1% concentration (by weight per article). Products manufactured and marketed by Fairchild Semiconductor do not contain substances on the REACH SVHC candidate list (as published by the ECHA on the following publication dates) in concentrations greater than 0.1% by weight per article:

October 28, 2008; January 13, 2010; March 30, 2010; June 18, 2010; December 15, 2010; June 20, 2011; December 19, 2011; June 18, 2012*; December 19, 2012; June 20, 2013, December 16, 2013; June 16, 2014.

Fairchild Semiconductor will continue to monitor the developments of REACH and is committed to meeting our responsibilities as an environmentally-responsible company. Please refer to the web site below for additional information regarding SVHC:

[ECHA European Chemical Agency](http://echa.europa.eu)

* Diboron trioxide was added to REACH Annex XIV as a Substance of Very High Concern(SVHC) on June 18, 2012. Fairchild products in glass encapsulated packages may list Diboron trioxide as a constituent material in the glass encapsulation, in a concentration greater than 0.1%; REACH classifies; glass as a substance of unknown or variable composition, complex reaction products or biological matter (UVCB) containing the elements silica, calcium, sodium, potassium, magnesium and other cautions bonded together with oxygen. In glass, these elements are bonded into a non crystalline molecular structure with completely different properties than the starting material; Therefore Diboron trioxide is not present in the finished Fairchild product and does not require notification of the presents of a SVHC.

Joint Industry Guide (JIG) 101

With the exception of RoHS exemptions listed above (if applicable), this product does not contain any restricted substances listed in the Joint Industry Guide (JIG) 101 in concentrations greater than the threshold listed. The list of JIG substances may be viewed using this web link.

[Joint Industry Guide \(JIG\) 101](#)

The signature below is of the Company's designated personnel with delegated product ecology compliance responsibility and verifies that to the best of our knowledge the statements above are valid and accurate.

David Lancaster



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Environmental Declaration

The content of this document is based upon information collected from Fairchild Semiconductor's supply chain, manufacturing facilities and affiliates worldwide. Providing for limitations below, Fairchild Semiconductor certifies that the information provided in this document is correct as of the date indicated on this page.

Fairchild has implemented systems to ensure our products are compliant to environmental regulations and laws worldwide. However, not all materials in Fairchild's products may have been independently verified regarding substance content. In the event of any issues arising from information in this document, the warranty section of Fairchild's standard terms and conditions of sale shall apply, unless alternate contracts have been agreed upon in writing by both parties.